

Title (en)

APPARATUS FOR FORMING A CONNECTION THROUGH A BOARD

Title (de)

VORRICHTUNG ZUR HERSTELLUNG EINER VERBINDUNG DURCH EINE PLATTE

Title (fr)

APPAREIL PERMETTANT DE FORMER UNE CONNEXION A TRAVERS UNE CARTE

Publication

**EP 0995239 B1 20020320 (EN)**

Application

**EP 98928488 A 19980706**

Priority

- EP 98928488 A 19980706
- EP 97111702 A 19970710
- IB 9801035 W 19980706

Abstract (en)

[origin: WO9903173A1] An apparatus is specified for through-plating a board (1), in particular a circuit board, having electric contacts (6, 7) which extend from one side of the board (1) to the other, having a receptacle (4), arranged on one side of the board, for an electric plug (14) with a screen (16), and having contacts for making contact with the screen, which likewise extend through the board (1). The contacts for making contact with the screen are constructed in two parts, the first part comprises a contact pin, a press-in zone for pressing into a bore in the board (1) and an extended region (23) adjacent to the press-in zone, and the second part (26) is held in an outer wall (19, 20) of the receptacle (4) and has a first resilient region (28) for making contact with the extended region (23) of the first part and a second resilient region (27) for making contact with the screen (16).

IPC 1-7

**H01R 12/16**; **H01R 13/658**

IPC 8 full level

**H01R 13/658** (2011.01)

CPC (source: EP)

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Citation (examination)

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